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ABSTRACT OF THE DISCLOSURE

A holding member, which beforehand fixedly holds a semiconductor laser element and has thermal conductivity, is fixed to a base member, which is fixed to a case and which has thermal conductivity, by the use of a thermal type adhesive member having thermal conductivity so that the semiconductor laser element is disposed at a predetermined optical position where optical adjustment has been carried out with respect to an optical system of the case.

COPIES TO BE MADE